



DOCKET # 0057-2608-2Y

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :

Toshiaki SHINOHARA, et al.

: EXAMINER: C. Chu

SERIAL NO: 09/534,043 :

FILED: March 24, 2000

: GROUP ART UNIT: 2815

FOR: SEMICONDUCTOR MODULE AND INSULATING SUBSTRATE THEREFOR

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS  
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated October 4, 2001, please amend the above-identified application as follows:

**IN THE DRAWINGS**

Please amend Figure 9 according to the attached Letter Requesting Approval of Drawing Changes.

**IN THE CLAIMS**

Please cancel claims ~~2~~, ~~11~~, and ~~12~~.

Please amend claims 1, 3-4, 7-9, and 13 as shown in clean form below. A marked up copy of these amended claims is attached hereto.

1. (Amended) A semiconductor module mountable on an external heat sink, said semiconductor module comprising:

an insulating substrate for said semiconductor module, said insulating substrate including a substrate, a first conductive pattern formed on a first main surface of said substrate which is on the opposite side from said external heat sink, and a second conductive

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